

PROTECTION PRODUCTS

Description

RailClamp® TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. They are designed to replace 0201 size multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and other portable electronics. This device offers desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

RClamp®5011ZA features extremely good ESD protection characteristics highlighted by low typical dynamic resistance of 0.25 Ohms, low peak ESD clamping voltage, and high ESD withstand voltage (+/-15kV contact per IEC 61000-4-2). Low maximum capacitance (0.45pF at VR=0V) minimizes loading on sensitive circuits. Each device will protect one high-speed data line operating at 5 Volts.

RClamp5011ZA is in a 2-pin SLP0603P2X3F package measuring 0.6 x 0.3 mm with a nominal height of only 0.25mm. Leads are finished with NiAu. The small package gives the designer the flexibility to protect single lines in applications where arrays are not practical. The combination of small size and high ESD surge capability makes them ideal for use in applications such as cellular phones, displays, and tablet PC's.

Features

- High ESD withstand Voltage: +/-15kV (Contact) and +/- 18kV (Air) per IEC 61000-4-2
- Ultra-small package
- Protects one data line
- Low ESD clamping voltage
- Working voltage: 5V
- Low capacitance: 0.45pF maximum
- Low leakage current
- Extremely low dynamic resistance: 0.25 Ohms (Typ)
- Solid-state silicon-avalanche technology

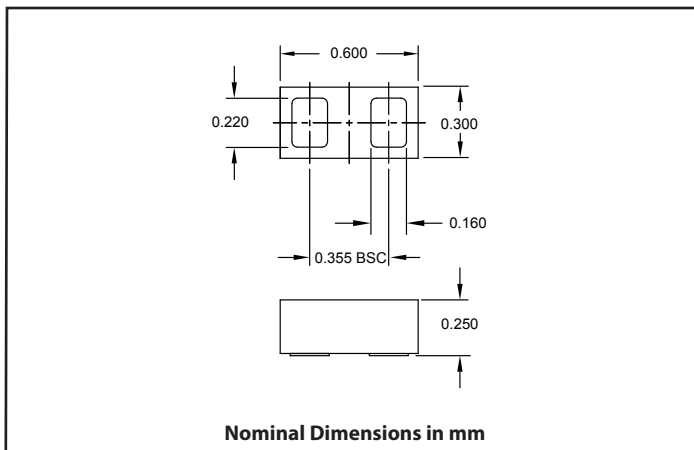
Mechanical Characteristics

- SLP0603P2X3F package
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Nominal Dimensions: 0.6 x 0.3 x 0.25 mm
- Lead Finish: NiAu
- Marking: Marking code
- Packaging: Tape and Reel

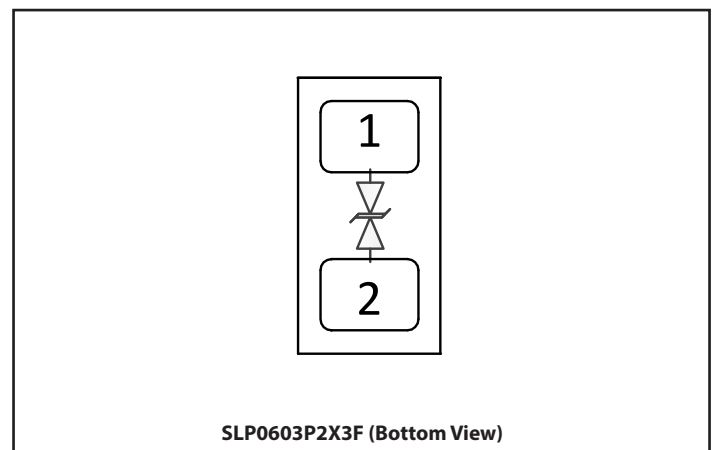
Applications

- HDMI
- USB 3.0
- MiPi / MDDI
- MHL
- FM Antenna

Package Dimension



Schematic & Pin Configuration



Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PK}	50	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	4	A
ESD per IEC 61000-4-2 (Air) ⁽¹⁾ ESD per IEC 61000-4-2 (Contact) ⁽¹⁾	V_{ESD}	± 18 ± 15	kV
Operating Temperature	T_J	-40 to +85	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

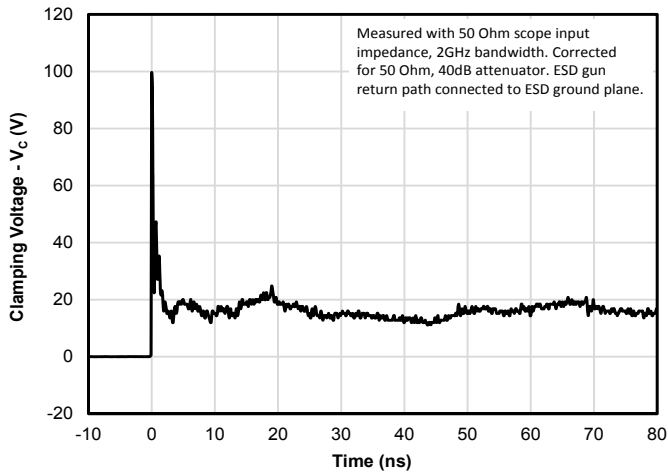
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}	T=-40 to +85°C			5	V
Reverse Breakdown Voltage	V_{BR}	$I_{PT} = 1mA$	6.5	7.5	10	V
Reverse Leakage Current	I_R	$V_{RWM} = 5V$		<5	50	nA
Clamping Voltage	V_C	$I_{PP} = 2A, t_p = 8/20\mu s$			11.5	V
		$I_{PP} = 4A, t_p = 8/20\mu s$			12.5	V
ESD Clamping Voltage ⁽²⁾	V_C	$I_{PP} = 4A, t_p = 0.2/100ns$		8.5		V
		$I_{PP} = 16A, t_p = 0.2/100ns$		11.5		V
Dynamic Resistance ^{(2), (3)}	R_{DYN}	$t_p = 0.2/100ns$		0.25		Ω
Junction Capacitance	C_J	$V_R = 0V, f = 1MHz$		0.40	0.45	pF

Notes

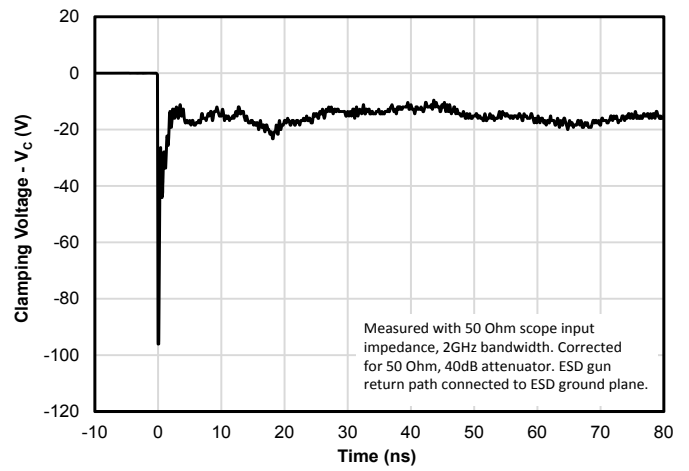
- 1) Measured with a 40dB attenuator, 50 Ohm scope input impedance, 2GHz bandwidth. ESD gun return path connected to ESD ground plane.
- 2) Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.
- 3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

Typical Characteristics

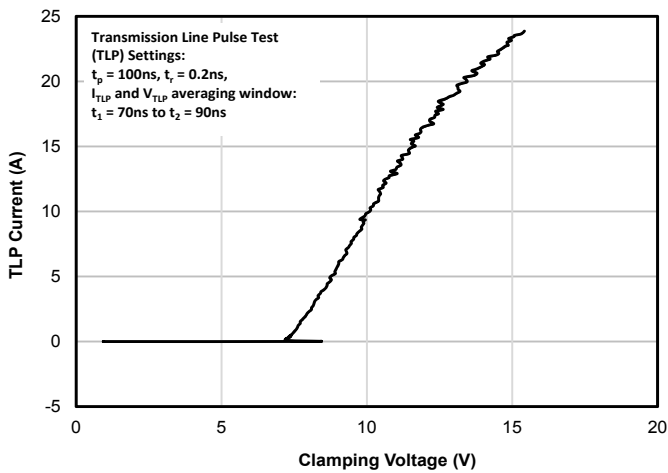
ESD Clamping (8kV Contact per IEC 61000-4-2)



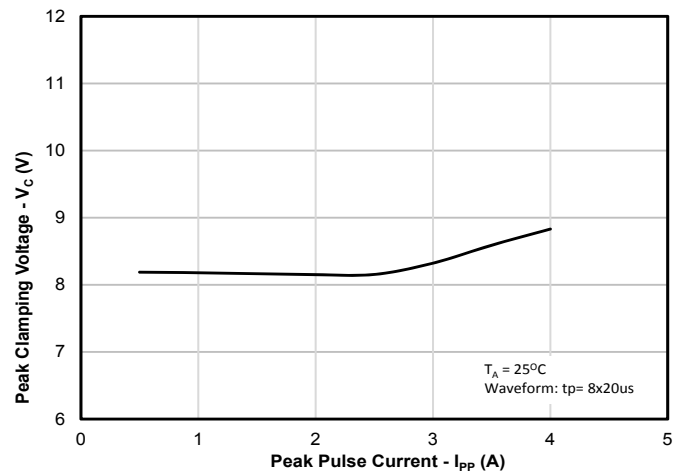
ESD Clamping (-8kV Contact per IEC 61000-4-2)



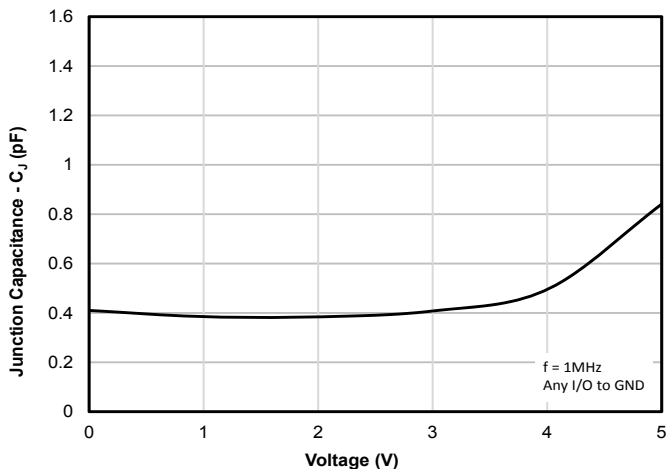
TLP Characteristic



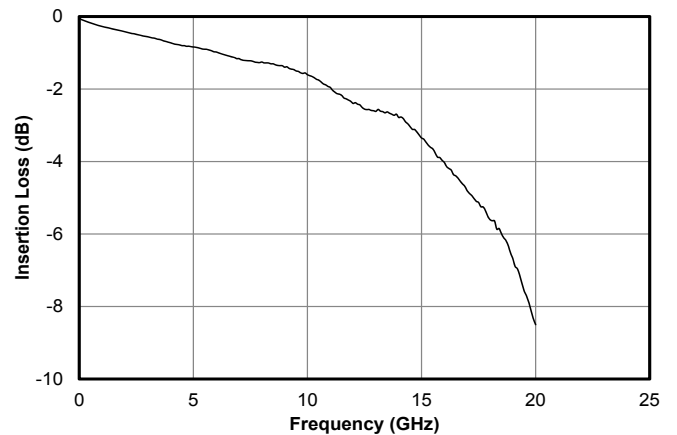
Clamping Voltage vs. Peak Pulse Current ($t_p=8/20\mu\text{s}$)



Capacitance vs. Reverse Voltage

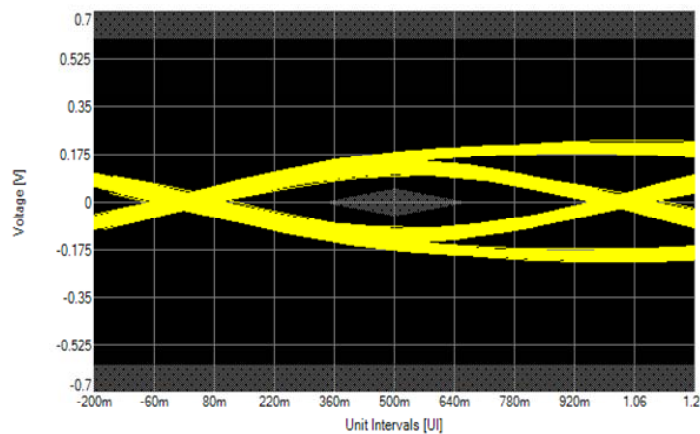


Insertion Loss-S21 (dB)

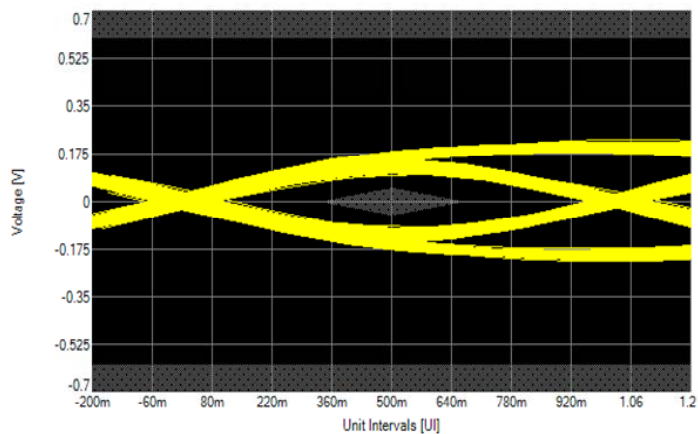


Typical Characteristics (Continued)

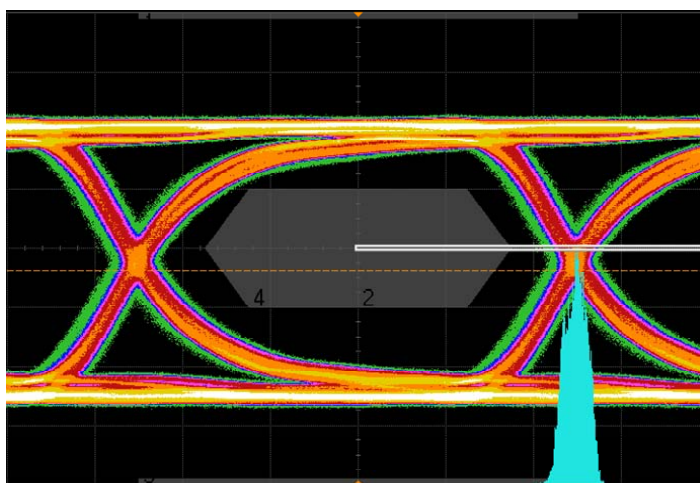
USB3.0 Eye Pattern without RClamp5011ZA



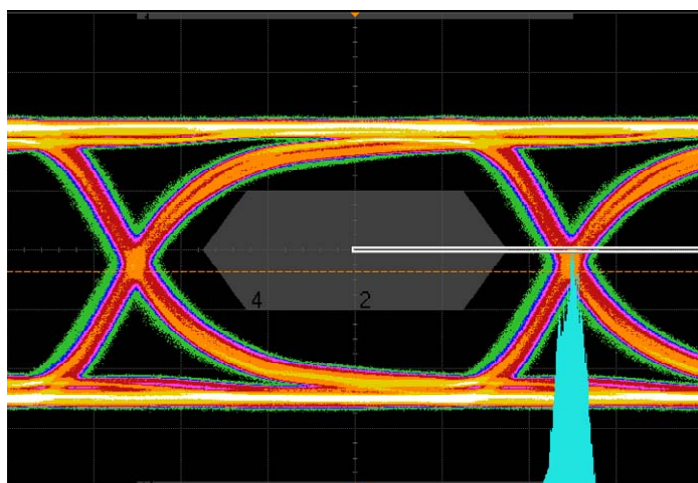
USB3.0 Eye Pattern with RClamp5011ZA



HDMI 1.4 Eye Pattern without RClamp5011ZA



HDMI 1.4 Eye Pattern with RClamp5011ZA



Application Information

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable-solder joints. The figure at the right details Semtech's recommended mounting pattern. Recommended assembly guidelines are shown in Table 1. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing-parameters will require some experimentation to get the desired solder application. Semtech's recommended-mounting pattern is based on the following design guidelines:

Land Pattern

The recommended land pattern follows IPC standards and is designed for maximum solder coverage. Detailed dimensions are shown elsewhere in this document.

Solder Stencil

Stencil design is one of the key factors which will determine the volume of solder paste which is deposited onto the land pad. The area ratio of the stencil aperture will determine how well the stencil will print. The area ratio takes into account the aperture shape, aperture size, and stencil thickness. An area ratio of 0.70 – 0.75 is preferred for the subject package. The area ratio of a rectangular aperture is given as:

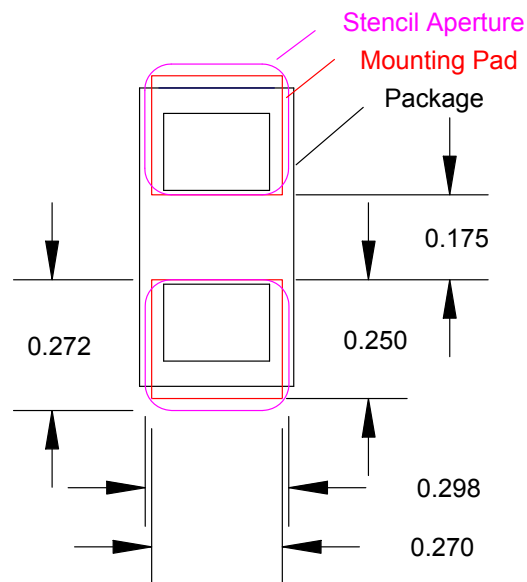
Area Ratio = (L * W) / (2 * (L + W) * T)

Where:

- L = Aperture Length
- W = Aperture Width
- T = Stencil Thickness

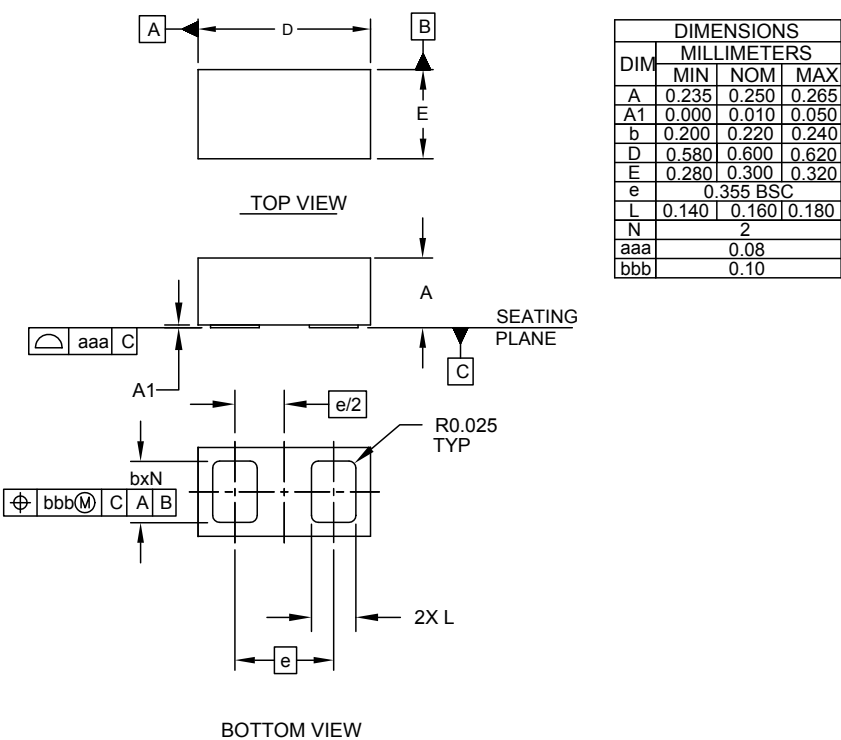
Semtech recommends a stencil thickness of 0.100mm for this device. The stencil should be laser cut with electropolishedfinish. The stencil should have a positive taper of approximately 5 degrees. Electro polishing and tapering the walls results in reduced surface friction and better paste release. For small pitch components, Semtech recommends a square aperture with rounded corners for consistent solder release. Due to the small aperture size, a solder paste with Type 4 or smaller particles are recommended.

Recommended Mounting Pattern



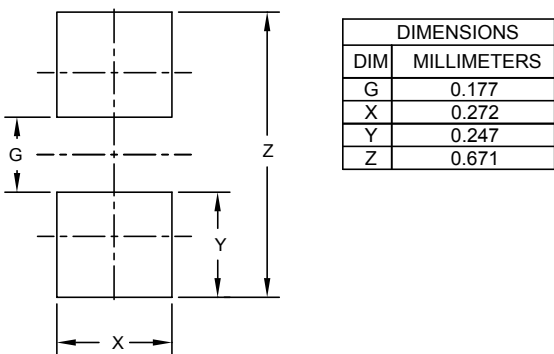
Assembly Parameter	Recommendation
Solder Stencil Design	Laser cut, Electro-polished
Aperture shape	Rectangular with rounded corners
Solder Stencil Thickness	0.100 mm (0.004")
Solder Paste Type	Type 4 size sphere or smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Non-Solder mask defined
PCB Pad Finish	OSP OR NiAu

Outline Drawing - SLP0603P2X3F



NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - SLP0603P2X3F



NOTES:
CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
COMPANY'S MANUFACTURING GUIDELINES ARE MET.

A rectangular box with a black border, containing the lowercase letter y in the center.

Technical drawing of a control panel showing a front view and a cross-section A-A.

Front View Dimensions:

- Overall width: 8.00 ± 0.10
- Overall height: 1.75 ± 0.05
- Distance between centerlines of top row components: 2.00 ± 0.05
- Distance between centerlines of bottom row components: 2.00 ± 0.05
- Distance between centerlines of top and bottom rows: 3.50 ± 0.05
- Distance from left edge to centerline of first component: 0.42 ± 0.03
- Distance from centerline of last component to right edge: 0.39 ± 0.03
- Distance from left edge to centerline of first component (bottom row): 0.69 ± 0.03
- Distance from centerline of last component (bottom row) to right edge: 0.29 ± 0.02

Cross-section A-A Dimensions:

- Panel thickness: 0.42 ± 0.03
- Mounting flange thickness: 0.69 ± 0.03
- Mounting hole diameter: 0.29 ± 0.02
- Mounting hole diameter: $\phi 1.50^{+0.10}_{-0.00}$

Notes:

- ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.

Part Number	Qty per Reel	Reel Size
RClamp5011ZATFT	15,000	7"

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